FIG. 1

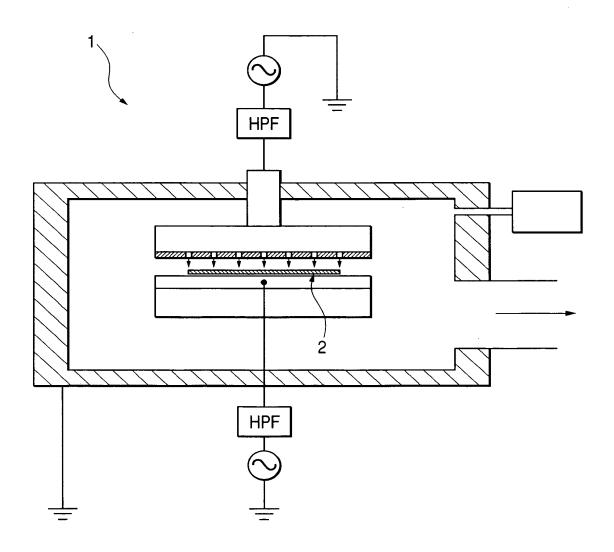


FIG. 2

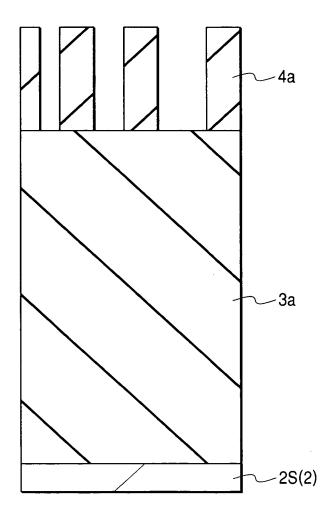


FIG. 3

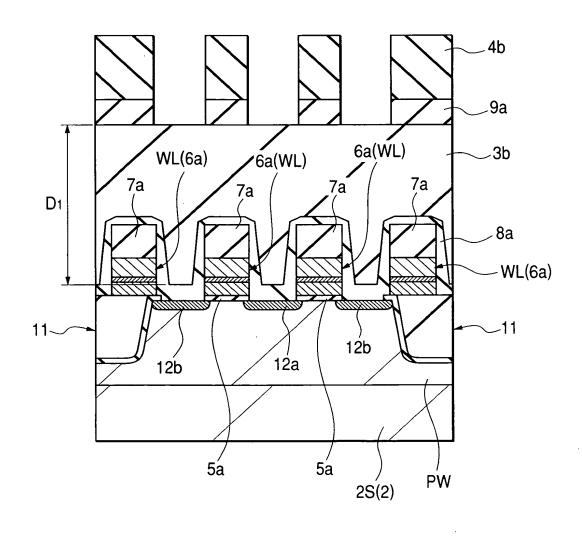


FIG. 4(a)

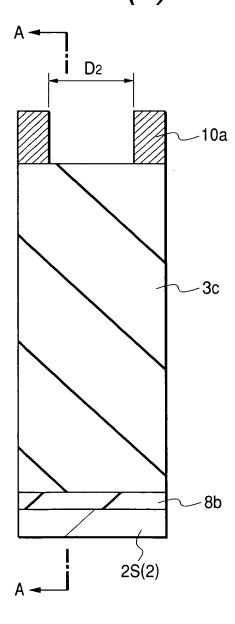


FIG. 4(b)

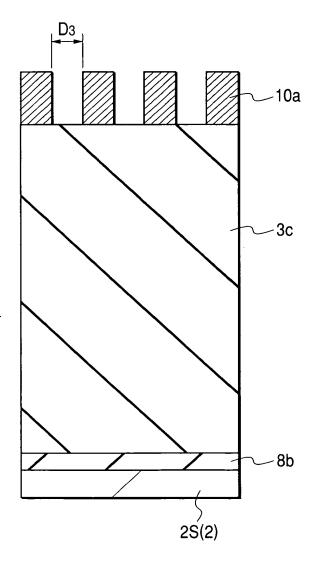


FIG. 5

FIG. 6

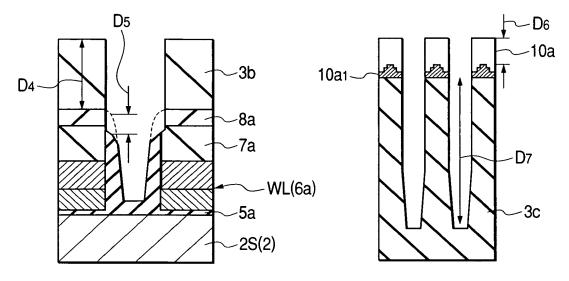


FIG. 7

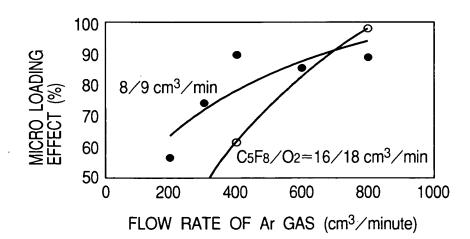


FIG. 8(a)

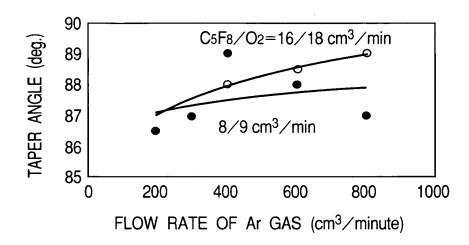
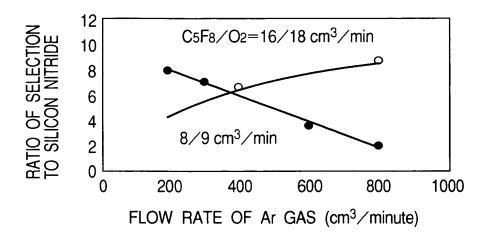


FIG. 8(b)





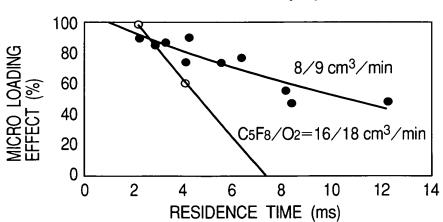


FIG. 9(b)

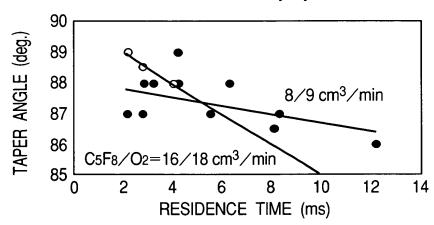
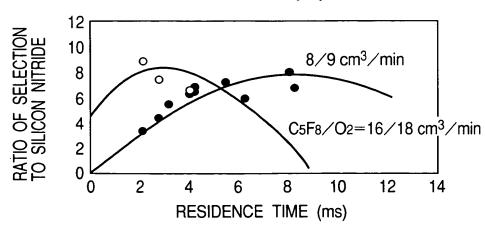
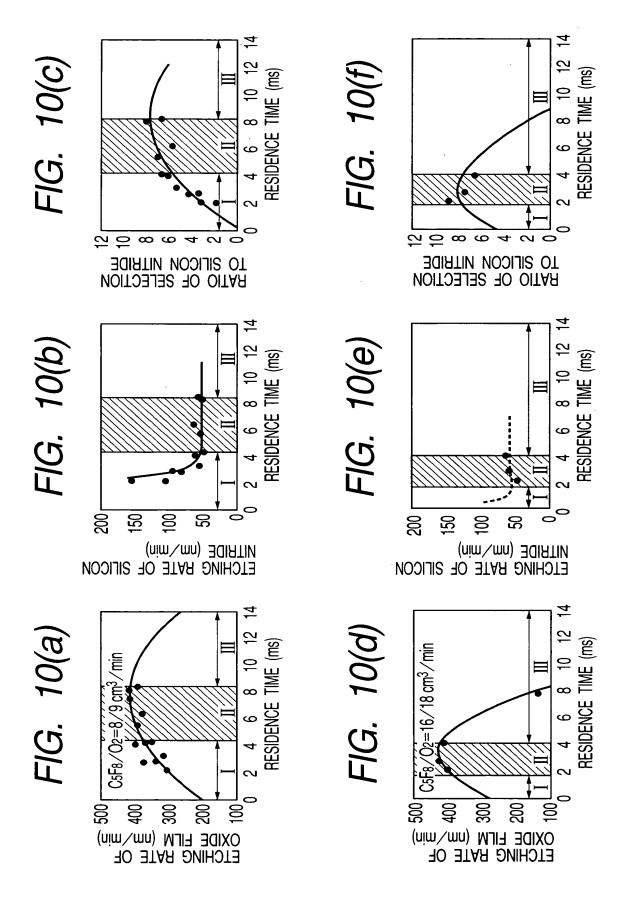


FIG. 9(c)





a 4 3

FIG. 11(a)

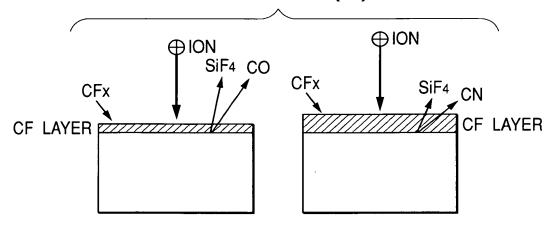


FIG. 11(b)

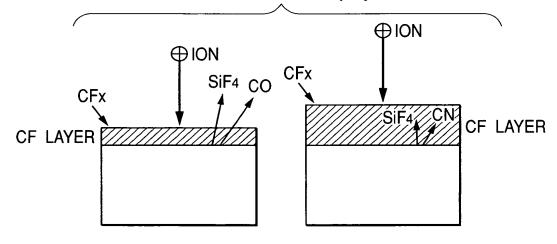


FIG. 11(c)

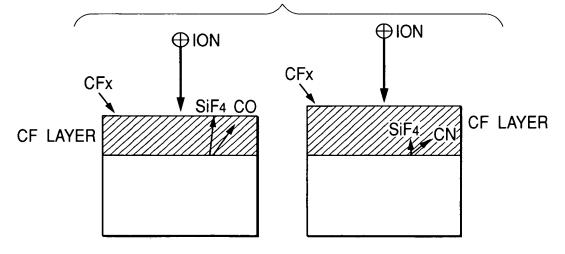
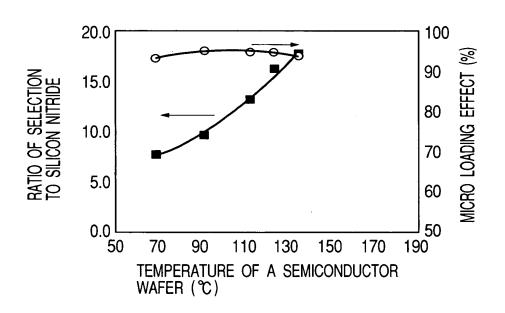


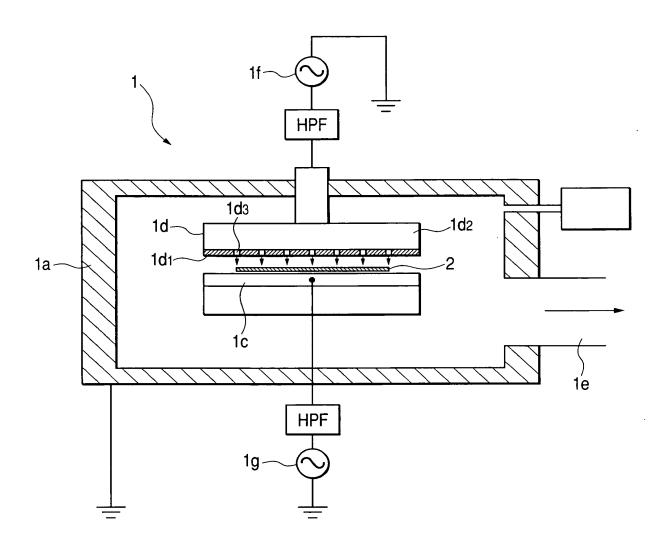
FIG. 12



PRESSURE			[Pa]	2.66
RF POWER	UPPER PO	RTION	[W]	800
	LOWER PO	RTION	[W]	700
FLOW RATE	OF C5F8	[cm ³ /r	minute]	16
FLOW RATE	OF O2	[cm ³ /r	minute]	18
FLOW RATE	OF Ar	[cm ³ /r	minute]	800
ELECTRODE				
UPPER PORTION (°C			(℃)	60
	LOWER PO	ORTION	(℃)	20
TEMPERATURE OF WALL SURFACE				50
ELECTRODE	GAP		[mm]	21

PRESSURE			[Pa]	2.66
RF POWER	UPPER PORT	ION	[W]	1800
	LOWER POR	TION	[W]	1500
FLOW RATE	OF C5F8	[cm ³ /n	ninute]	24
FLOW RATE	OF O ₂	[cm ³ /n	ninute]	28
FLOW RATE	OF Ar	[cm ³ /n	ninute]	700
ELECTRODE				
	UPPER POR	TION	(℃)	60
	LOWER POF	RTION	(℃)	20
TEMPERATU	50			
ELECTRODE	GAP		[mm]	19

FIG. 15



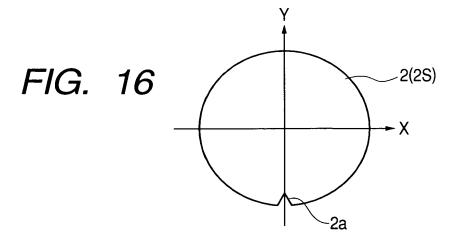


FIG. 17

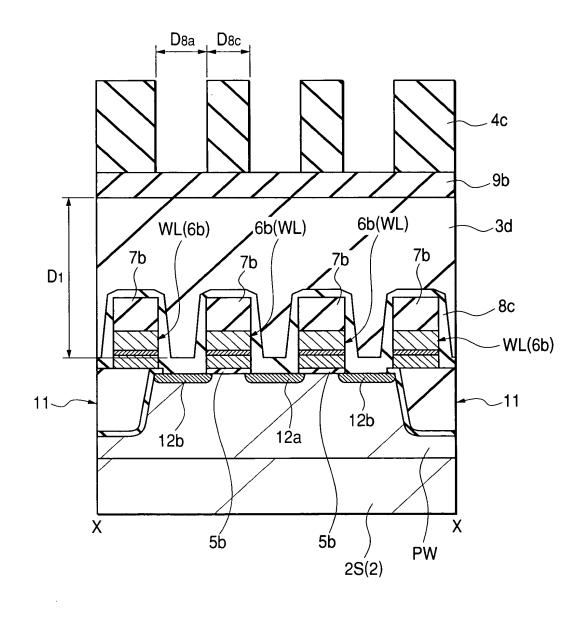


FIG. 18

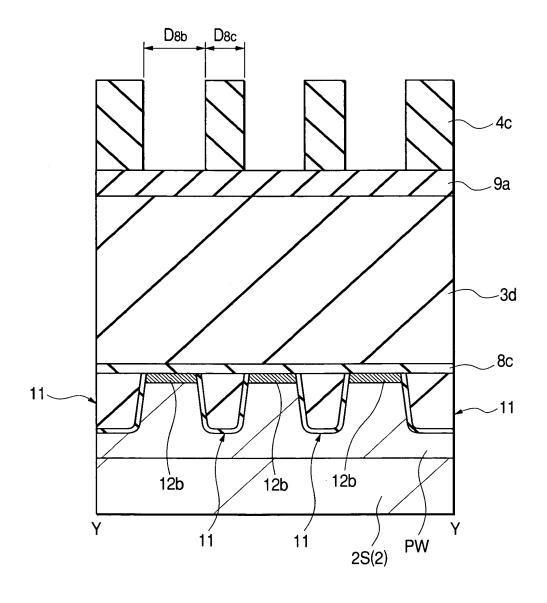


FIG. 19

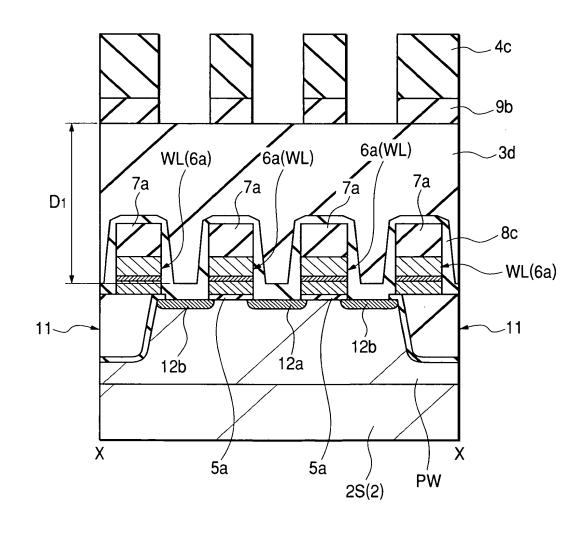
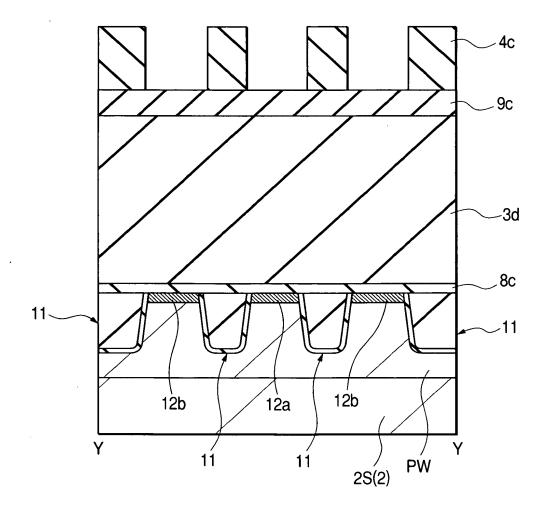
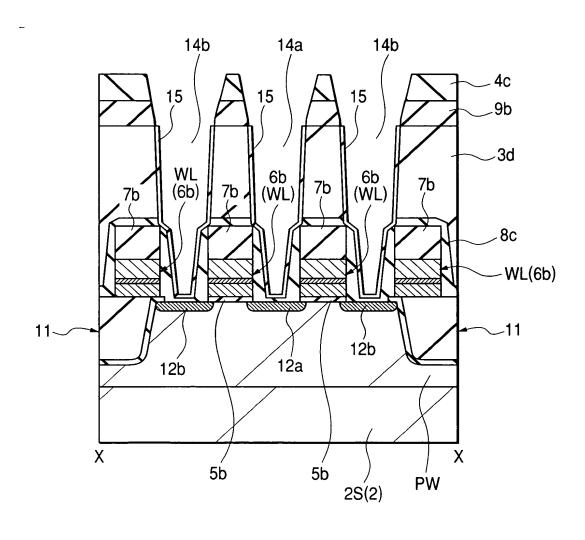


FIG. 20





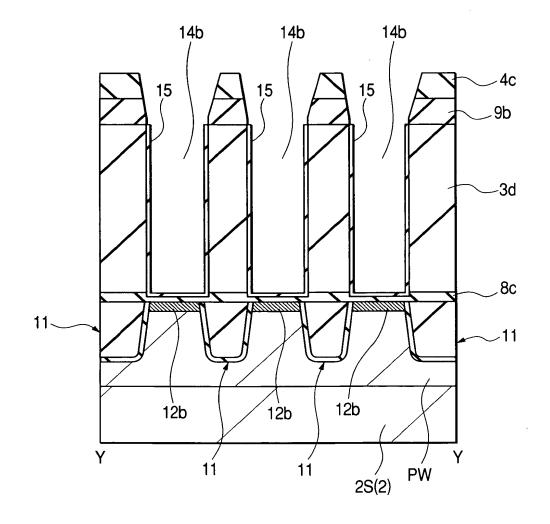
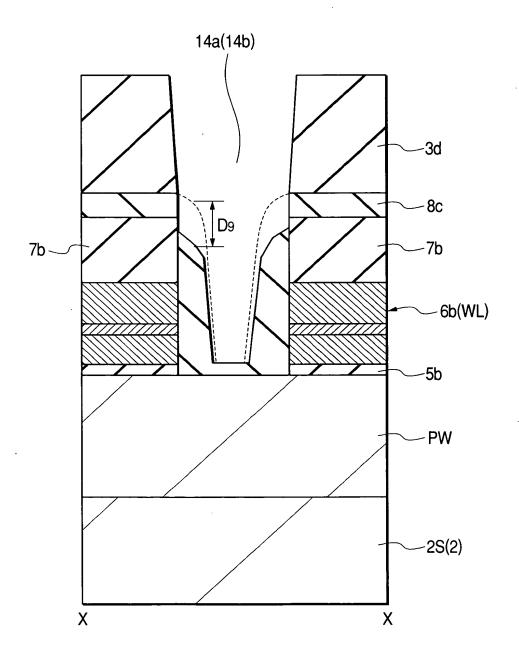


FIG. 23



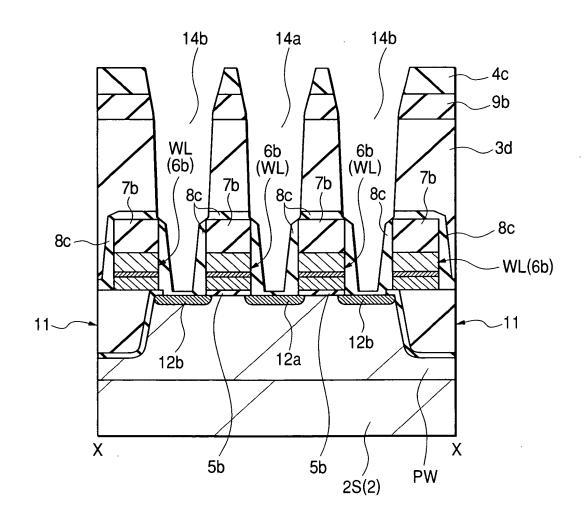
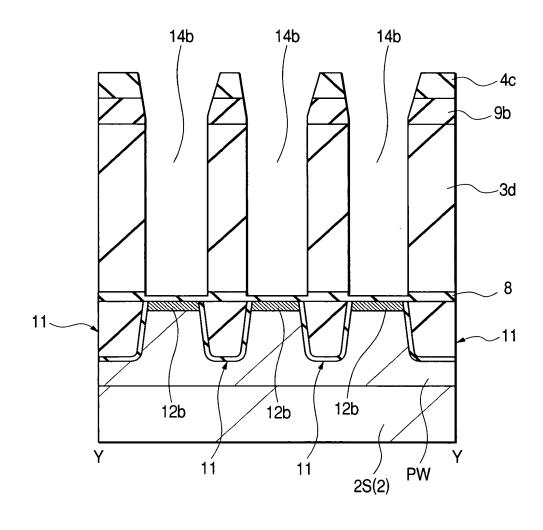
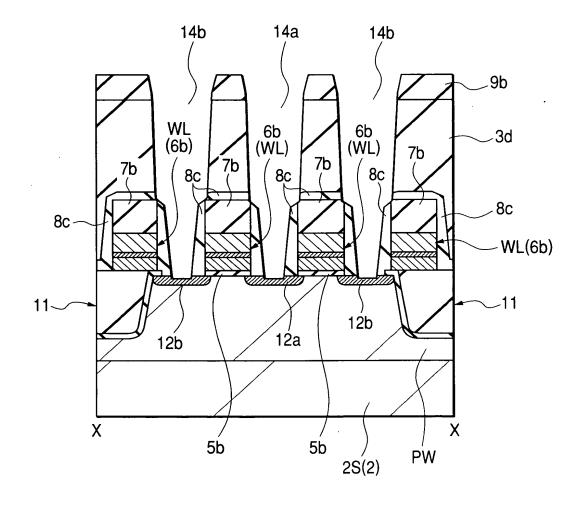


FIG. 25





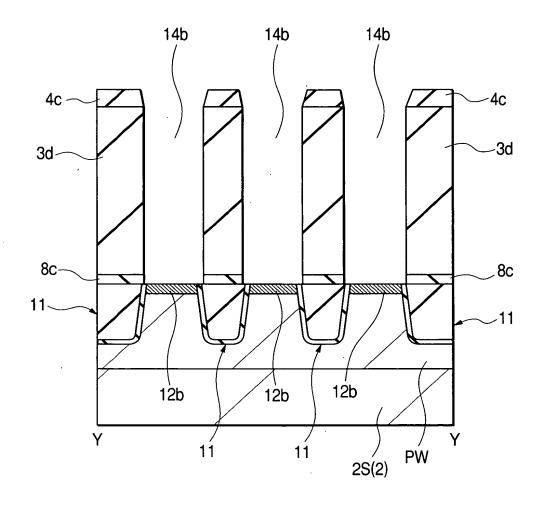
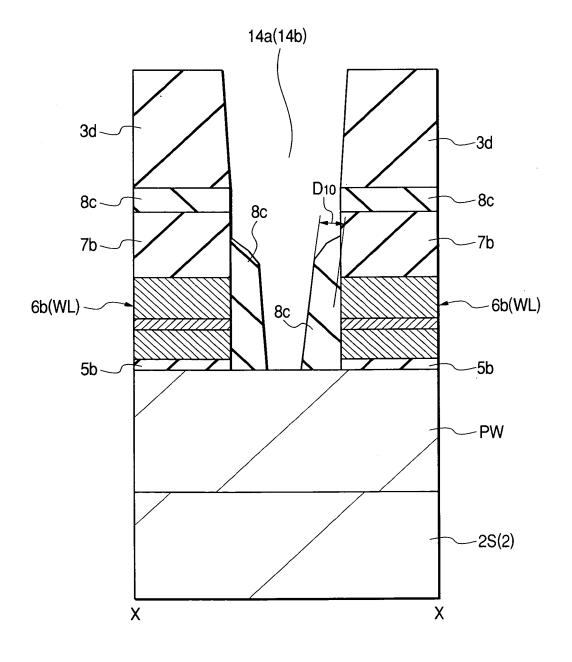


FIG. 28



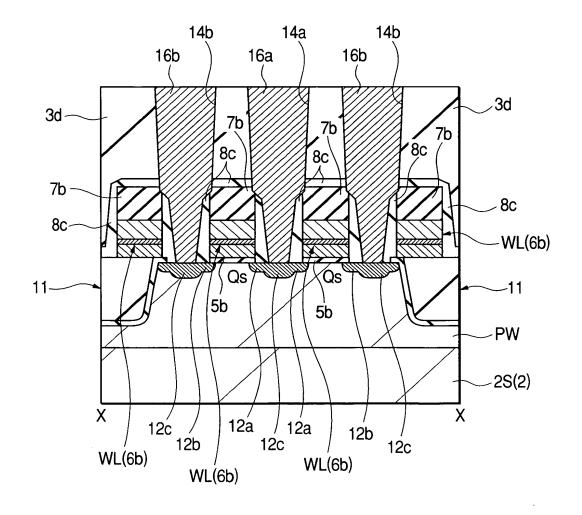


FIG. 30

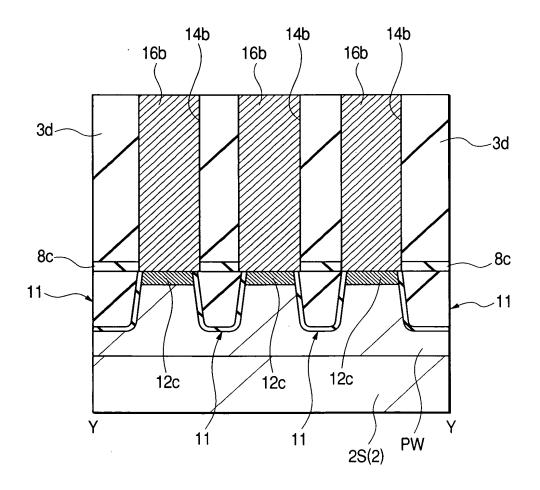


FIG. 31

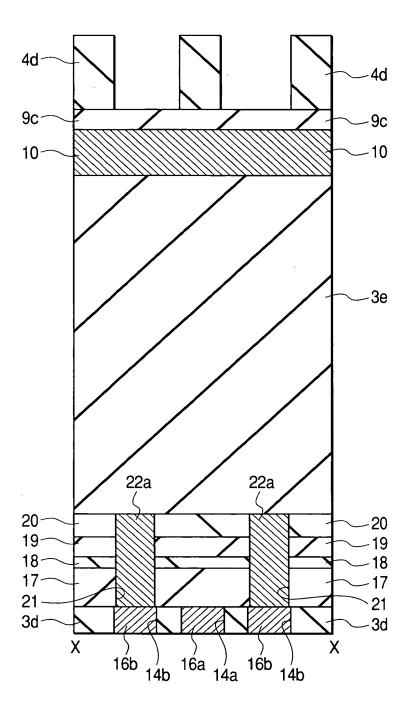


FIG. 32

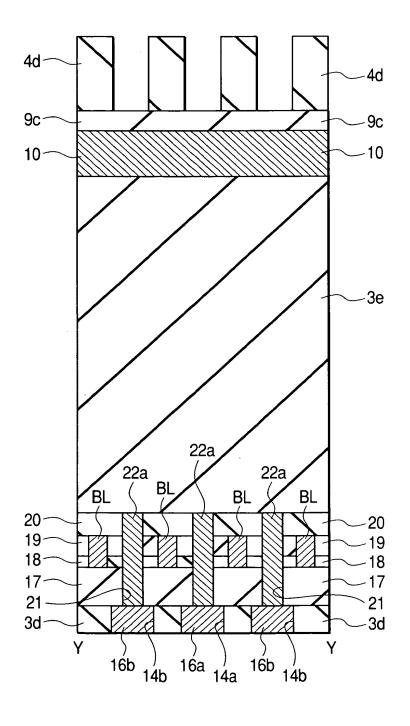


FIG. 33

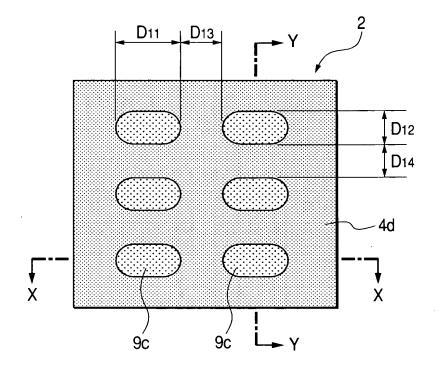


FIG. 34

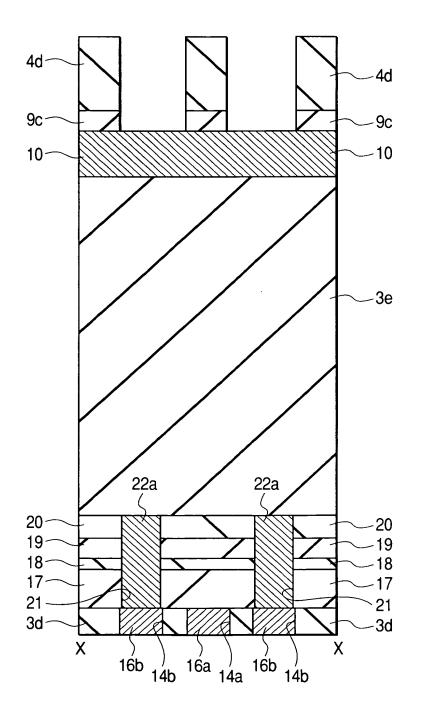


FIG. 35

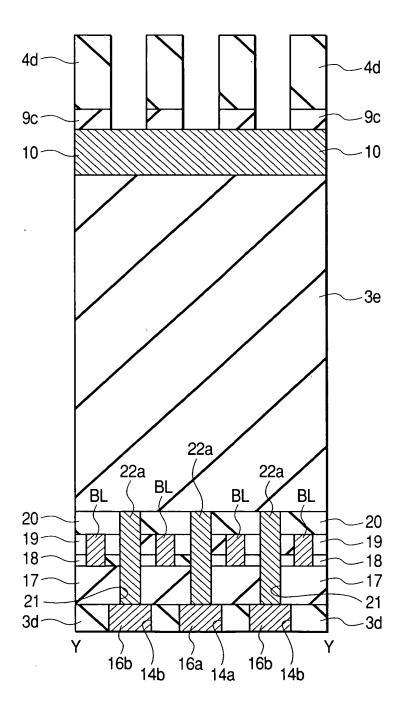


FIG. 36

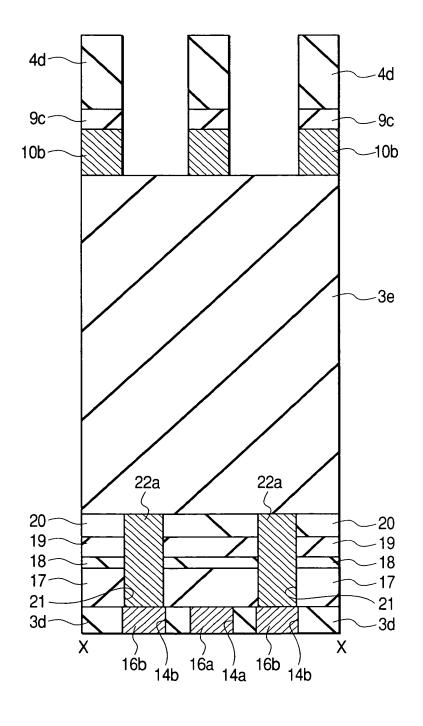


FIG. 37

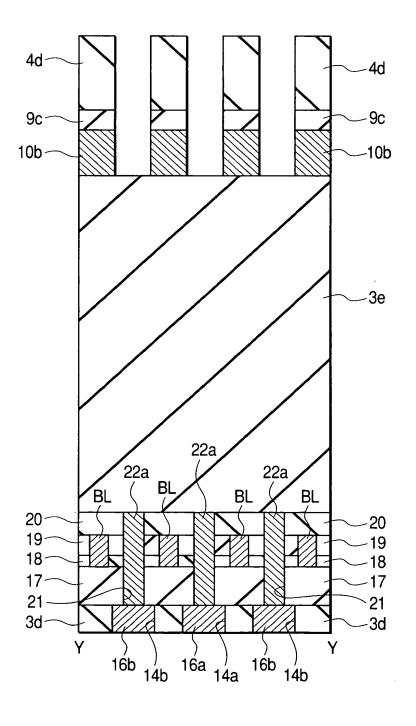


FIG. 38

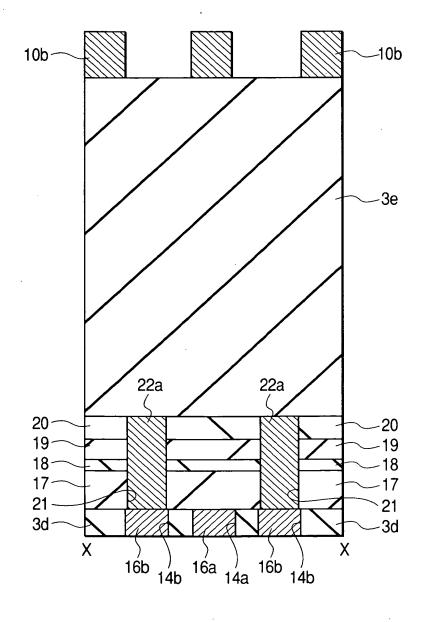


FIG. 39

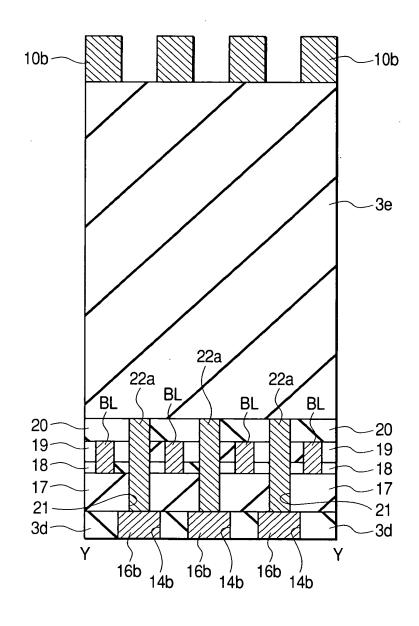
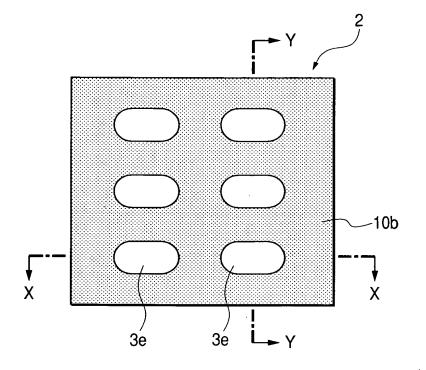


FIG. 40



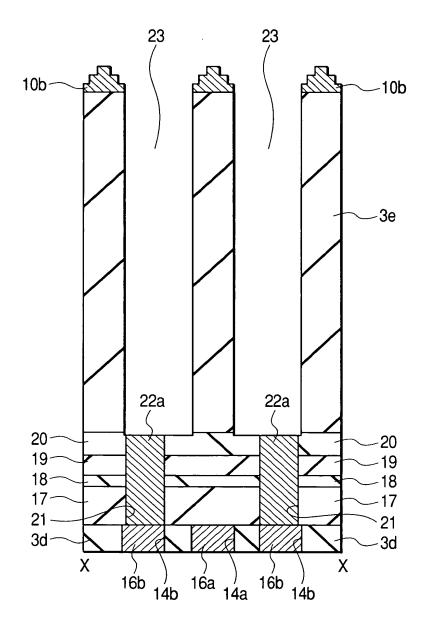


FIG. 42

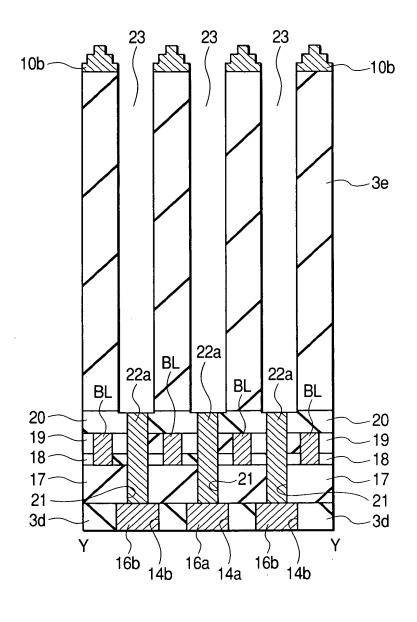


FIG. 43

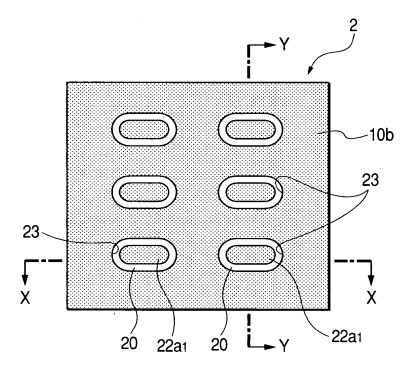


FIG. 44

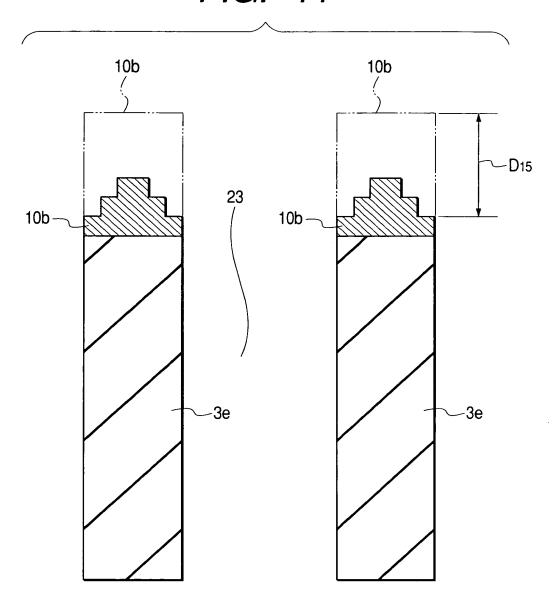


FIG. 45

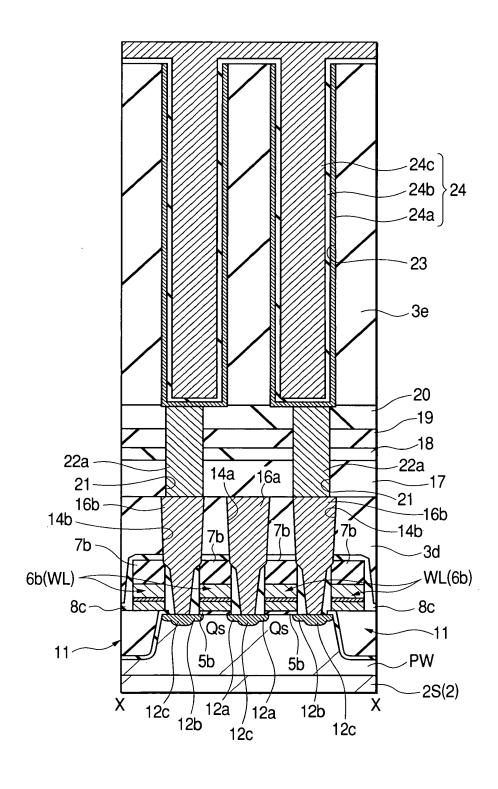
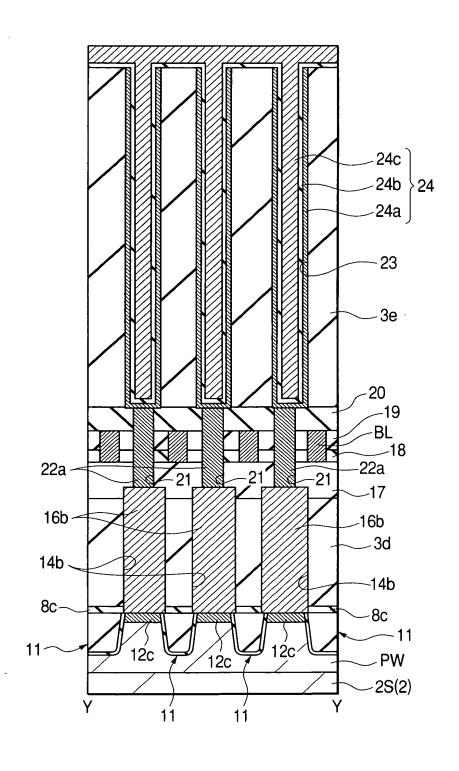


FIG. 46



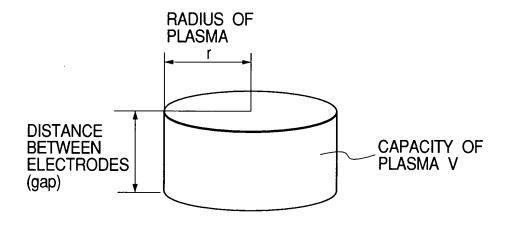


FIG. 48

